# **SWITCHMODE™ Power Rectifier**

# D<sup>2</sup>PAK Surface Mount Power Package

The D2PAK Power Rectifier is a state-of-the-art device that employs the use of the Schottky Barrier principle with a platinum barrier metal.

#### **Features**

- Package Designed for Power Surface Mount Applications
- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared!
- Similar in Size to Industry Standard TO-220 Package
- Pb-Free Packages are Available

#### **Mechanical Characteristics**

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C >400 V Human Body Model, 3B >8000 V

## MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	٧
Average Rectified Forward Current (Rated V <sub>R</sub> , T <sub>C</sub> = 110°C) Total Device	I <sub>F(AV)</sub>	10 20	Α
Peak Repetitive Forward Current (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 100^{\circ}C$ )	I <sub>FRM</sub>	20	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	150	Α
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I <sub>RRM</sub>	0.5	Α
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +175	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

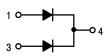
1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .



# ON Semiconductor®

http://onsemi.com

# SCHOTTKY BARRIER RECTIFIER **20 AMPERES 100 VOLTS**





D<sup>2</sup>PAK **CASE 418B** 

# **MARKING DIAGRAM**



= Assembly Location Α

Υ = Year WW = Work Week B20100 = Device Code = Pb-Free Package G **AKA** = Diode Polarity

## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

#### THERMAL CHARACTERISTICS (Per Leg)

	Characteristic	Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case Junction-to-Ambient (Note 2)	$R_{ hetaJC} \ R_{ hetaJA}$	2.0 50	°C/W

# **ELECTRICAL CHARACTERISTICS** (Per Leg)

Maximum Instantaneous Forward Voltage (Note 3)	$ \begin{aligned} &(i_F = 10 \text{ Amp, } T_C = 125^{\circ}\text{C}) \\ &(i_F = 10 \text{ Amp, } T_C = 25^{\circ}\text{C}) \\ &(i_F = 20 \text{ Amp, } T_C = 125^{\circ}\text{C}) \\ &(i_F = 20 \text{ Amp, } T_C = 25^{\circ}\text{C}) \end{aligned} $	VF	0.75 0.85 0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 3)	(Rated dc Voltage, T <sub>J</sub> = 125°C) (Rated dc Voltage, T <sub>J</sub> = 25°C)	İR	6.0 0.1	mA

- 2. When mounted using minimum recommended pad size on FR-4 board.
- 3. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MBRB20100CT	D <sup>2</sup> PAK	50 Units / Rail
MBRB20100CTG	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail
MBRB20100CTT4	D <sup>2</sup> PAK	800 Units / Tape & Reel
MBRB20100CTT4G	D <sup>2</sup> PAK (Pb-Free)	800 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

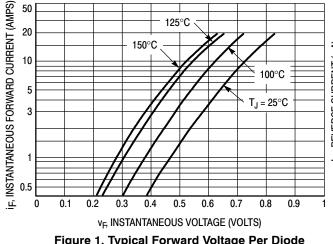


Figure 1. Typical Forward Voltage Per Diode

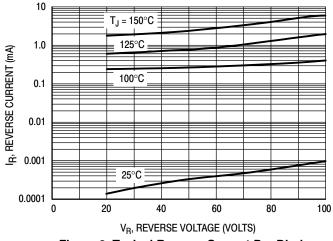


Figure 2. Typical Reverse Current Per Diode

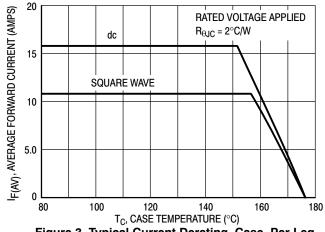


Figure 3. Typical Current Derating, Case, Per Leg

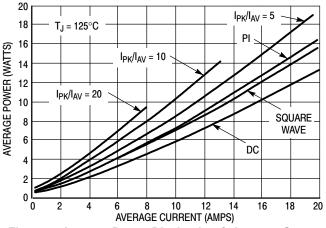
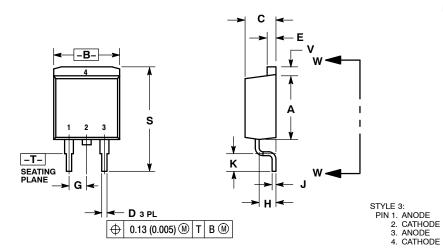


Figure 4. Average Power Dissipation & Average Current

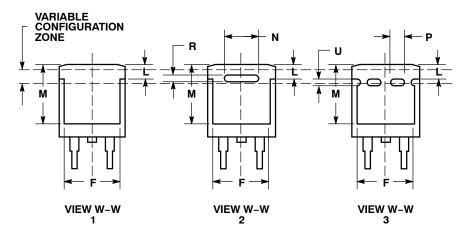
### **PACKAGE DIMENSIONS**

# D<sup>2</sup>PAK CASE 418B-04 **ISSUE K**

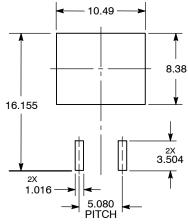


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
E	0.045	0.055	1.14	1.40	
F	0.310	0.350	7.87	8.89	
G	0.100 BSC		2.54 BSC		
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
K	0.090	0.110	2.29	2.79	
L	0.052	0.072	1.32	1.83	
M	0.280	0.320	7.11	8.13	
N	0.197 REF		5.00 REF		
Р	0.079	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF		
S	0.575	0.625	14.60	15.88	
٧	0.045	0.055	1.14	1.40	



### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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